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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	285
Number of Logic Elements/Cells	2280
Total RAM Bits	28262
Number of I/O	211
Number of Gates	-
Voltage - Supply	1.71V ~ 3.465V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	256-LFBGA, CSPBGA
Supplier Device Package	256-CABGA (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lcmxo2280c-4b256i

The devices use look-up tables (LUTs) and embedded block memories traditionally associated with FPGAs for flexible and efficient logic implementation. Through non-volatile technology, the devices provide the single-chip, high-security, instant-on capabilities traditionally associated with CPLDs. Finally, advanced process technology and careful design will provide the high pin-to-pin performance also associated with CPLDs.

The ispLEVER® design tools from Lattice allow complex designs to be efficiently implemented using the MachXO family of devices. Popular logic synthesis tools provide synthesis library support for MachXO. The ispLEVER tools use the synthesis tool output along with the constraints from its floor planning tools to place and route the design in the MachXO device. The ispLEVER tool extracts the timing from the routing and back-annotates it into the design for timing verification.

Architecture Overview

The MachXO family architecture contains an array of logic blocks surrounded by Programmable I/O (PIO). Some devices in this family have sysCLOCK PLLs and blocks of sysMEM™ Embedded Block RAM (EBRs). Figures 2-1, 2-2, and 2-3 show the block diagrams of the various family members.

The logic blocks are arranged in a two-dimensional grid with rows and columns. The EBR blocks are arranged in a column to the left of the logic array. The PIO cells are located at the periphery of the device, arranged into Banks. The PIOs utilize a flexible I/O buffer referred to as a sysIO interface that supports operation with a variety of interface standards. The blocks are connected with many vertical and horizontal routing channel resources. The place and route software tool automatically allocates these routing resources.

There are two kinds of logic blocks, the Programmable Functional Unit (PFU) and the Programmable Functional unit without RAM (PFF). The PFU contains the building blocks for logic, arithmetic, RAM, ROM, and register functions. The PFF block contains building blocks for logic, arithmetic, ROM, and register functions. Both the PFU and PFF blocks are optimized for flexibility, allowing complex designs to be implemented quickly and effectively. Logic blocks are arranged in a two-dimensional array. Only one type of block is used per row.

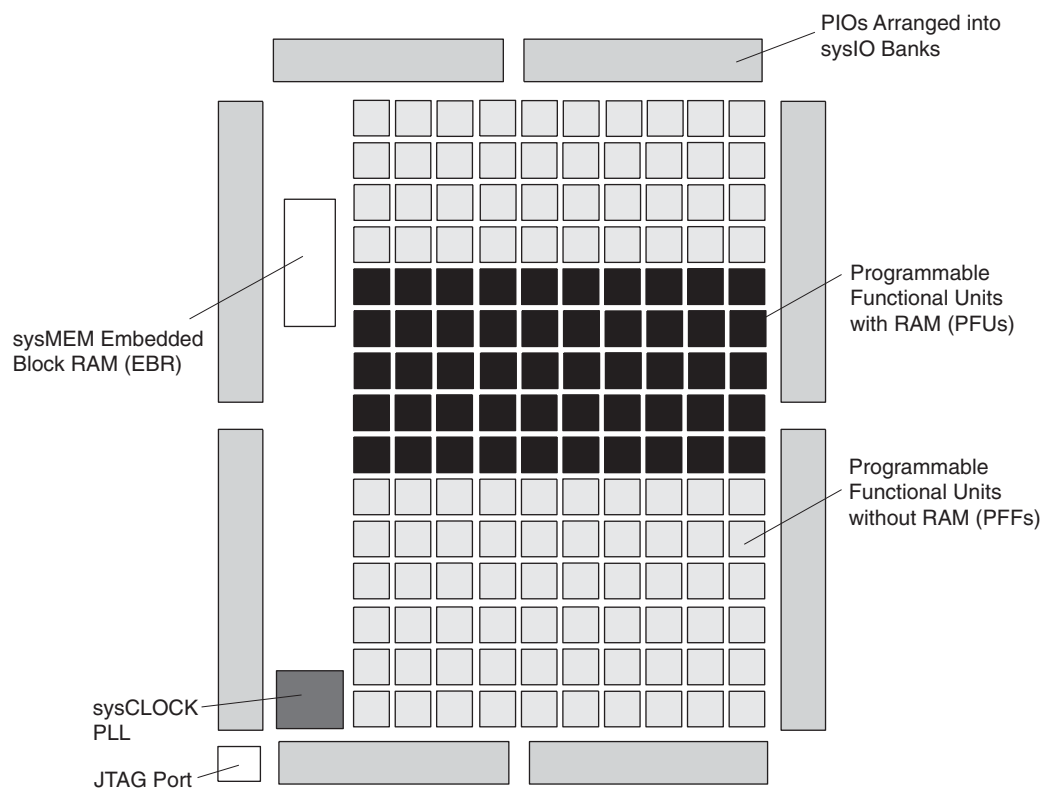
In the MachXO family, the number of sysIO Banks varies by device. There are different types of I/O Buffers on different Banks. See the details in later sections of this document. The sysMEM EBRs are large, dedicated fast memory blocks; these blocks are found only in the larger devices. These blocks can be configured as RAM, ROM or FIFO. FIFO support includes dedicated FIFO pointer and flag “hard” control logic to minimize LUT use.

The MachXO registers in PFU and sysI/O can be configured to be SET or RESET. After power up and device is configured, the device enters into user mode with these registers SET/RESET according to the configuration setting, allowing device entering to a known state for predictable system function.

The MachXO architecture provides up to two sysCLOCK™ Phase Locked Loop (PLL) blocks on larger devices. These blocks are located at either end of the memory blocks. The PLLs have multiply, divide, and phase shifting capabilities that are used to manage the frequency and phase relationships of the clocks.

Every device in the family has a JTAG Port that supports programming and configuration of the device as well as access to the user logic. The MachXO devices are available for operation from 3.3V, 2.5V, 1.8V, and 1.2V power supplies, providing easy integration into the overall system.

Figure 2-1. Top View of the MachXO1200 Device¹



1. Top view of the MachXO2280 device is similar but with higher LUT count, two PLLs, and three EBR blocks.

Figure 2-2. Top View of the MachXO640 Device

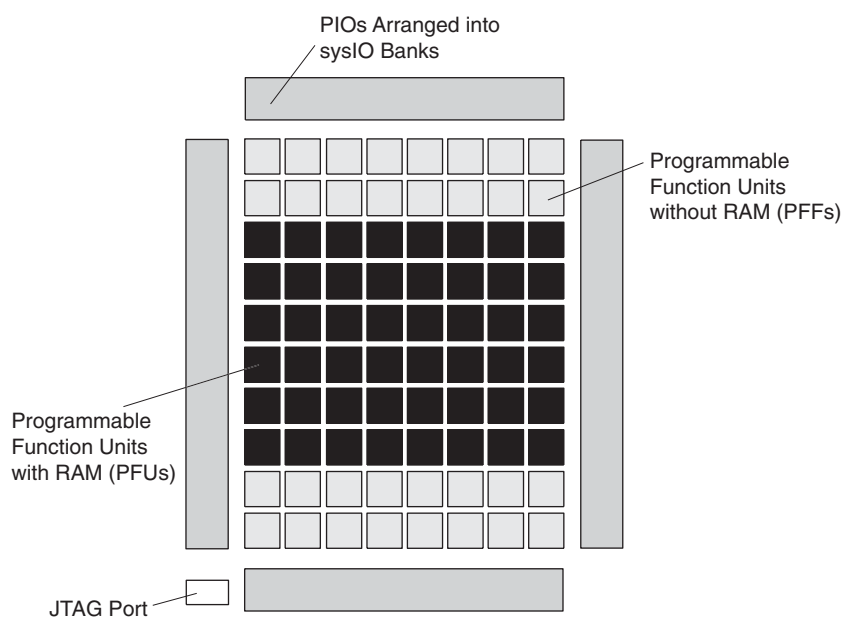


Table 2-5. PLL Signal Descriptions

Signal	I/O	Description
CLKI	I	Clock input from external pin or routing
CLKFB	I	PLL feedback input from PLL output, clock net, routing/external pin or internal feedback from CLKINTFB port
RST	I	"1" to reset the input clock divider
CLKOS	O	PLL output clock to clock tree (phase shifted/duty cycle changed)
CLKOP	O	PLL output clock to clock tree (No phase shift)
CLKOK	O	PLL output to clock tree through secondary clock divider
LOCK	O	"1" indicates PLL LOCK to CLKI
CLKINTFB	O	Internal feedback source, CLKOP divider output before CLOCKTREE
DDAMODE	I	Dynamic Delay Enable. "1": Pin control (dynamic), "0": Fuse Control (static)
DDAIZR	I	Dynamic Delay Zero. "1": delay = 0, "0": delay = on
DDAILAG	I	Dynamic Delay Lag/Lead. "1": Lag, "0": Lead
DDAIDEL[2:0]	I	Dynamic Delay Input

For more information on the PLL, please see details of additional technical documentation at the end of this data sheet.

sysMEM Memory

The MachXO1200 and MachXO2280 devices contain sysMEM Embedded Block RAMs (EBRs). The EBR consists of a 9-Kbit RAM, with dedicated input and output registers.

sysMEM Memory Block

The sysMEM block can implement single port, dual port, pseudo dual port, or FIFO memories. Each block can be used in a variety of depths and widths as shown in Table 2-6.

Table 2-6. sysMEM Block Configurations

Memory Mode	Configurations
Single Port	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 9 512 x 18 256 x 36
True Dual Port	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 9 512 x 18
Pseudo Dual Port	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 9 512 x 18 256 x 36
FIFO	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 9 512 x 18 256 x 36

PIO Groups

On the MachXO devices, PIO cells are assembled into two different types of PIO groups, those with four PIO cells and those with six PIO cells. PIO groups with four IOs are placed on the left and right sides of the device while PIO groups with six IOs are placed on the top and bottom. The individual PIO cells are connected to their respective sysIO buffers and PADs.

On all MachXO devices, two adjacent PIOs can be joined to provide a complementary Output driver pair. The I/O pin pairs are labeled as "T" and "C" to distinguish between the true and complement pins.

The MachXO1200 and MachXO2280 devices contain enhanced I/O capability. All PIO pairs on these larger devices can implement differential receivers. In addition, half of the PIO pairs on the left and right sides of these devices can be configured as LVDS transmit/receive pairs. PIOs on the top of these larger devices also provide PCI support.

Figure 2-15. Group of Four Programmable I/O Cells

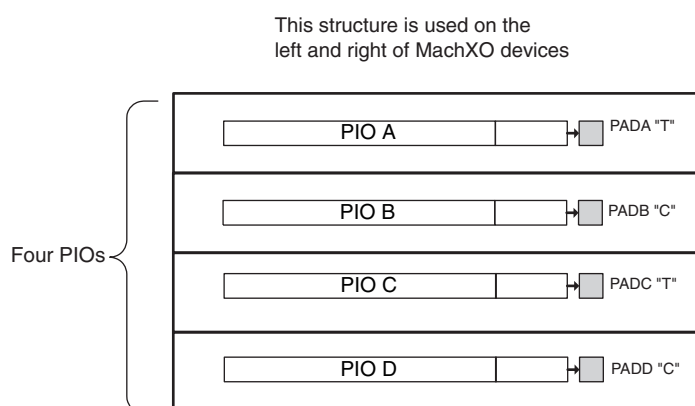
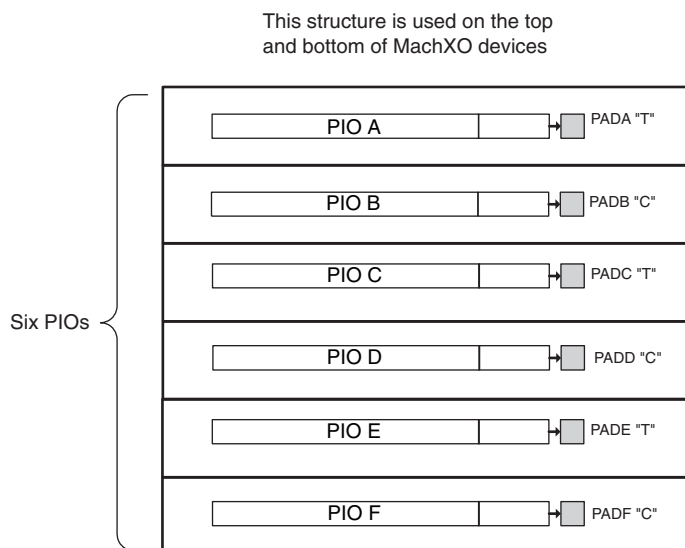


Figure 2-16. Group of Six Programmable I/O Cells



PIO

The PIO blocks provide the interface between the sysIO buffers and the internal PFU array blocks. These blocks receive output data from the PFU array and a fast output data signal from adjacent PFUs. The output data and fast

Table 2-10. Supported Output Standards

Output Standard	Drive	V _{CCIO} (Typ.)
Single-ended Interfaces		
LVTTTL	4mA, 8mA, 12mA, 16mA	3.3
LVC MOS33	4mA, 8mA, 12mA, 14mA	3.3
LVC MOS25	4mA, 8mA, 12mA, 14mA	2.5
LVC MOS18	4mA, 8mA, 12mA, 14mA	1.8
LVC MOS15	4mA, 8mA	1.5
LVC MOS12	2mA, 6mA	1.2
LVC MOS33, Open Drain	4mA, 8mA, 12mA, 14mA	—
LVC MOS25, Open Drain	4mA, 8mA, 12mA, 14mA	—
LVC MOS18, Open Drain	4mA, 8mA, 12mA, 14mA	—
LVC MOS15, Open Drain	4mA, 8mA	—
LVC MOS12, Open Drain	2mA, 6mA	—
PCI33 ³	N/A	3.3
Differential Interfaces		
LVDS ^{1, 2}	N/A	2.5
BLVDS, RSDS ²	N/A	2.5
LVPECL ²	N/A	3.3

1. MachXO1200 and MachXO2280 devices have dedicated LVDS buffers.

2. These interfaces can be emulated with external resistors in all devices.

3. Top Banks of MachXO1200 and MachXO2280 devices only.

sysIO Buffer Banks

The number of Banks vary between the devices of this family. Eight Banks surround the two larger devices, the MachXO1200 and MachXO2280 (two Banks per side). The MachXO640 has four Banks (one Bank per side). The smallest member of this family, the MachXO256, has only two Banks.

Each sysIO buffer Bank is capable of supporting multiple I/O standards. Each Bank has its own I/O supply voltage (V_{CCIO}) which allows it to be completely independent from the other Banks. Figure 2-18, Figure 2-18, Figure 2-20 and Figure 2-21 shows the sysIO Banks and their associated supplies for all devices.

the system. These capabilities make the MachXO ideal for many multiple power supply and hot-swap applications.

Sleep Mode

The MachXO “C” devices ($V_{CC} = 1.8/2.5/3.3V$) have a sleep mode that allows standby current to be reduced dramatically during periods of system inactivity. Entry and exit to Sleep mode is controlled by the SLEEPN pin.

During Sleep mode, the logic is non-operational, registers and EBR contents are not maintained, and I/Os are tri-stated. Do not enter Sleep mode during device programming or configuration operation. In Sleep mode, power supplies are in their normal operating range, eliminating the need for external switching of power supplies. Table 2-11 compares the characteristics of Normal, Off and Sleep modes.

Table 2-11. Characteristics of Normal, Off and Sleep Modes

Characteristic	Normal	Off	Sleep
SLEEPN Pin	High	—	Low
Static Icc	Typical <10mA	0	Typical <100uA
I/O Leakage	<10μA	<1mA	<10μA
Power Supplies VCC/VCCIO/VCCAUX	Normal Range	0	Normal Range
Logic Operation	User Defined	Non Operational	Non operational
I/O Operation	User Defined	Tri-state	Tri-state
JTAG and Programming circuitry	Operational	Non-operational	Non-operational
EBR Contents and Registers	Maintained	Non-maintained	Non-maintained

SLEEPN Pin Characteristics

The SLEEPN pin behaves as an LVCMOS input with the voltage standard appropriate to the VCC supply for the device. This pin also has a weak pull-up, along with a Schmidt trigger and glitch filter to prevent false triggering. An external pull-up to VCC is recommended when Sleep Mode is not used to ensure the device stays in normal operation mode. Typically, the device enters sleep mode several hundred nanoseconds after SLEEPN is held at a valid low and restarts normal operation as specified in the Sleep Mode Timing table. The AC and DC specifications portion of this data sheet shows a detailed timing diagram.

Oscillator

Every MachXO device has an internal CMOS oscillator. The oscillator can be routed as an input clock to the clock tree or to general routing resources. The oscillator frequency can be divided by internal logic. There is a dedicated programming bit to enable/disable the oscillator. The oscillator frequency ranges from 18MHz to 26MHz.

Configuration and Testing

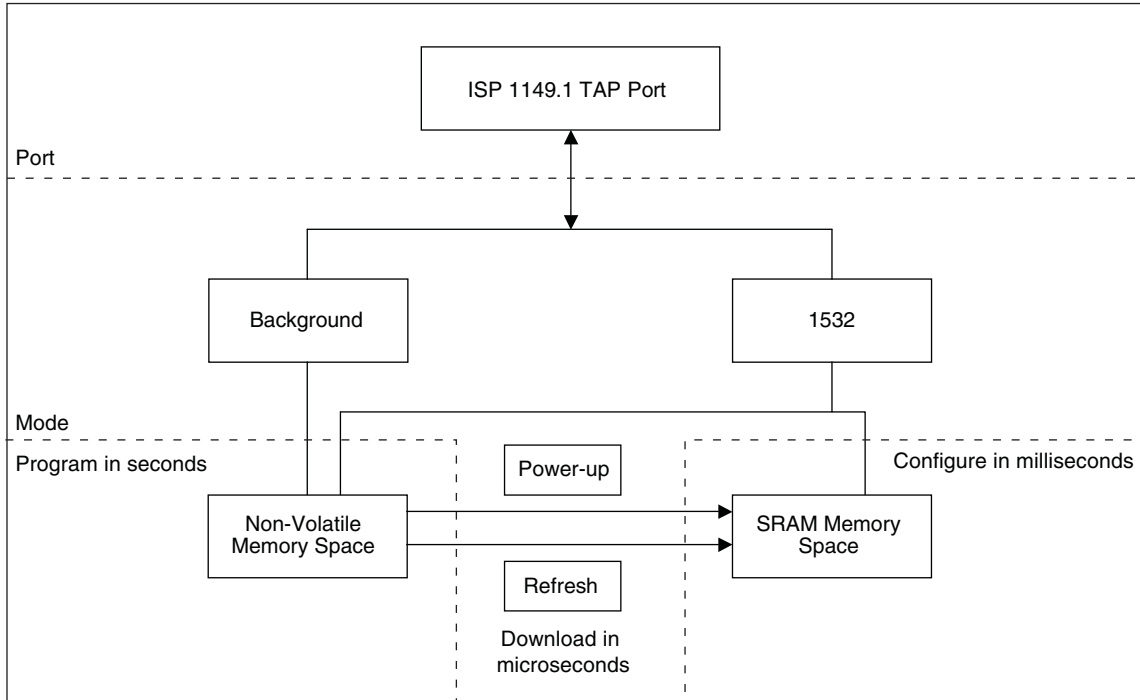
The following section describes the configuration and testing features of the MachXO family of devices.

IEEE 1149.1-Compliant Boundary Scan Testability

All MachXO devices have boundary scan cells that are accessed through an IEEE 1149.1 compliant test access port (TAP). This allows functional testing of the circuit board, on which the device is mounted, through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test data to be captured and shifted out for verification. The test access port consists of dedicated I/Os: TDI, TDO, TCK and TMS. The test access port shares its power supply with one of the VCCIO Banks (MachXO256: V_{CCIO1} ; MachXO640: V_{CCIO2} ; MachXO1200 and MachXO2280: V_{CCIO5}) and can operate with LVCMOS3.3, 2.5, 1.8, 1.5, and 1.2 standards.

For more details on boundary scan test, please see information regarding additional technical documentation at the end of this data sheet.

Figure 2-22. MachXO Configuration and Programming



Density Shifting

The MachXO family has been designed to enable density migration in the same package. Furthermore, the architecture ensures a high success rate when performing design migration from lower density parts to higher density parts. In many cases, it is also possible to shift a lower utilization design targeted for a high-density device to a lower density device. However, the exact details of the final resource utilization will impact the likely success in each case.

Initialization Supply Current^{1, 2, 3, 4}

Over Recommended Operating Conditions

Symbol	Parameter	Device	Typ. ⁵	Units
I_{CC}	Core Power Supply	LCMXO256C	13	mA
		LCMXO640C	17	mA
		LCMXO1200C	21	mA
		LCMXO2280C	23	mA
		LCMXO256E	10	mA
		LCMXO640E	14	mA
		LCMXO1200E	18	mA
		LCMXO2280E	20	mA
I_{CCAUX}	Auxiliary Power Supply $V_{CCAUX} = 3.3V$	LCMXO256E/C	10	mA
		LCMXO640E/C	13	mA
		LCMXO1200E/C	24	mA
		LCMXO2280E/C	25	mA
I_{CCIO}	Bank Power Supply ⁶	All devices	2	mA

1. For further information on supply current, please see details of additional technical documentation at the end of this data sheet.

2. Assumes all I/O pins are held at V_{CCIO} or GND.

3. Frequency = 0MHz.

4. Typical user pattern.

5. $T_J = 25^\circ C$, power supplies at nominal voltage.

6. Per Bank, $V_{CCIO} = 2.5V$. Does not include pull-up/pull-down.

Programming and Erase Flash Supply Current^{1, 2, 3, 4}

Symbol	Parameter	Device	Typ. ⁵	Units
I_{CC}	Core Power Supply	LCMXO256C	9	mA
		LCMXO640C	11	mA
		LCMXO1200C	16	mA
		LCMXO2280C	22	mA
		LCMXO256E	6	mA
		LCMXO640E	8	mA
		LCMXO1200E	12	mA
		LCMXO2280E	14	mA
I_{CCAUX}	Auxiliary Power Supply $V_{CCAUX} = 3.3V$	LCMXO256C/E	8	mA
		LCMXO640C/E	10	mA
		LCMXO1200E/E	15	mA
		LCMXO2280C/E	16	mA
I_{CCIO}	Bank Power Supply ⁶	All devices	2	mA

1. For further information on supply current, please see details of additional technical documentation at the end of this data sheet.

2. Assumes all I/O pins are held at V_{CCIO} or GND.

3. Typical user pattern.

4. JTAG programming is at 25MHz.

5. $T_J = 25^\circ C$, power supplies at nominal voltage.

6. Per Bank, $V_{CCIO} = 2.5V$. Does not include pull-up/pull-down.

sysIO Differential Electrical Characteristics

LVDS

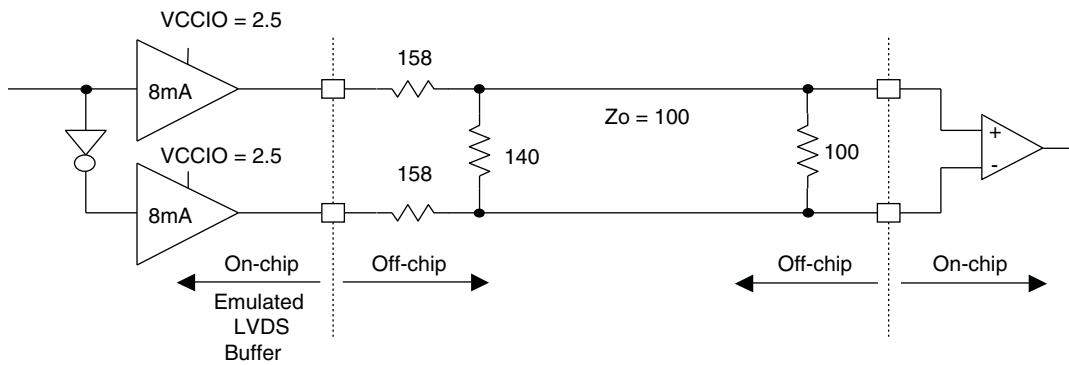
Over Recommended Operating Conditions

Parameter Symbol	Parameter Description	Test Conditions	Min.	Typ.	Max.	Units
V_{INP}, V_{INM}	Input Voltage		0	—	2.4	V
V_{THD}	Differential Input Threshold		+/-100	—	—	mV
V_{CM}	Input Common Mode Voltage	$100\text{mV} \leq V_{THD}$	$V_{THD}/2$	1.2	1.8	V
		$200\text{mV} \leq V_{THD}$	$V_{THD}/2$	1.2	1.9	V
		$350\text{mV} \leq V_{THD}$	$V_{THD}/2$	1.2	2.0	V
I_{IN}	Input current	Power on	—	—	+/-10	μA
V_{OH}	Output high voltage for V_{OP} or V_{OM}	$R_T = 100 \text{ Ohm}$	—	1.38	1.60	V
V_{OL}	Output low voltage for V_{OP} or V_{OM}	$R_T = 100 \text{ Ohm}$	0.9V	1.03	—	V
V_{OD}	Output voltage differential	$(V_{OP} - V_{OM}), R_T = 100 \text{ Ohm}$	250	350	450	mV
ΔV_{OD}	Change in V_{OD} between high and low		—	—	50	mV
V_{OS}	Output voltage offset	$(V_{OP} - V_{OM})/2, R_T = 100 \text{ Ohm}$	1.125	1.25	1.375	V
ΔV_{OS}	Change in V_{OS} between H and L		—	—	50	mV
I_{OSD}	Output short circuit current	$V_{OD} = 0\text{V}$ Driver outputs shorted	—	—	6	mA

LVDS Emulation

MachXO devices can support LVDS outputs via emulation (LVDS25E), in addition to the LVDS support that is available on-chip on certain devices. The output is emulated using complementary LVCMOS outputs in conjunction with resistors across the driver outputs on all devices. The scheme shown in Figure 3-1 is one possible solution for LVDS standard implementation. Resistor values in Figure 3-1 are industry standard values for 1% resistors.

Figure 3-1. LVDS Using External Resistors (LVDS25E)



Note: All resistors are $\pm 1\%$.

The LVDS differential input buffers are available on certain devices in the MachXO family.

Table 3-1. LVDS DC Conditions

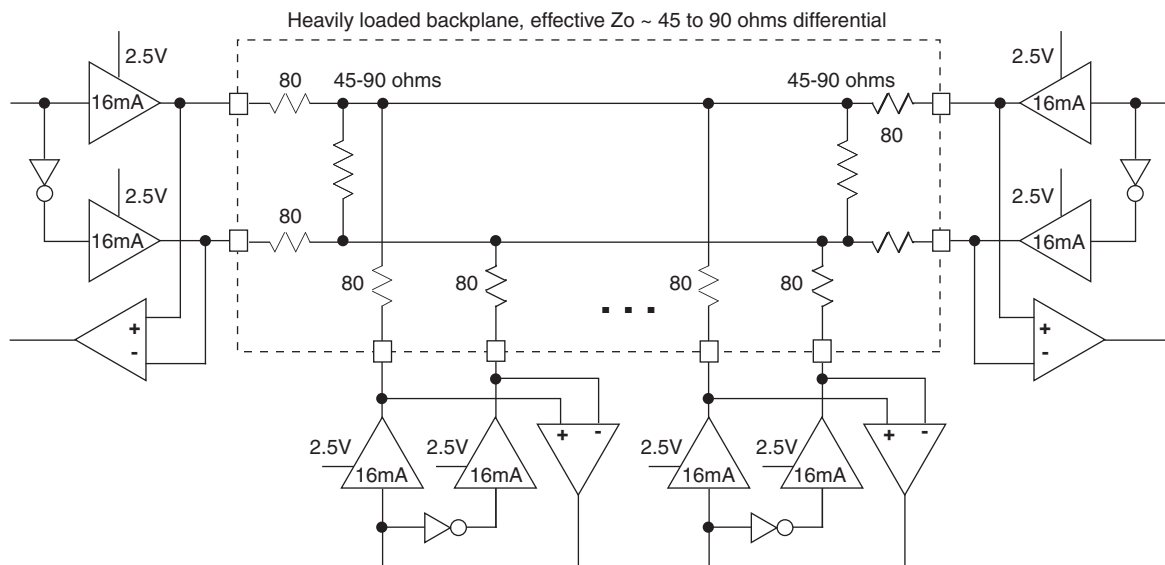
Over Recommended Operating Conditions

Parameter	Description	Typical	Units
Z_{OUT}	Output impedance	20	Ω
R_S	Driver series resistor	294	Ω
R_P	Driver parallel resistor	121	Ω
R_T	Receiver termination	100	Ω
V_{OH}	Output high voltage	1.43	V
V_{OL}	Output low voltage	1.07	V
V_{OD}	Output differential voltage	0.35	V
V_{CM}	Output common mode voltage	1.25	V
Z_{BACK}	Back impedance	100	Ω
I_{DC}	DC output current	3.66	mA

BLVDS

The MachXO family supports the BLVDS standard through emulation. The output is emulated using complementary LVCMOS outputs in conjunction with a parallel external resistor across the driver outputs. The input standard is supported by the LVDS differential input buffer on certain devices. BLVDS is intended for use when multi-drop and bi-directional multi-point differential signaling is required. The scheme shown in Figure 3-2 is one possible solution for bi-directional multi-point differential signals.

Figure 3-2. BLVDS Multi-point Output Example



MachXO Family Timing Adders^{1, 2, 3}

Over Recommended Operating Conditions

Buffer Type	Description	-5	-4	-3	Units
Input Adjusters					
LVDS25 ⁴	LVDS	0.44	0.53	0.61	ns
BLVDS25 ⁴	BLVDS	0.44	0.53	0.61	ns
LVPECL33 ⁴	LVPECL	0.42	0.50	0.59	ns
LVTTTL33	LVTTTL	0.01	0.01	0.01	ns
LVC MOS33	LVC MOS 3.3	0.01	0.01	0.01	ns
LVC MOS25	LVC MOS 2.5	0.00	0.00	0.00	ns
LVC MOS18	LVC MOS 1.8	0.07	0.08	0.10	ns
LVC MOS15	LVC MOS 1.5	0.14	0.17	0.19	ns
LVC MOS12	LVC MOS 1.2	0.40	0.48	0.56	ns
PCI33 ⁴	PCI	0.01	0.01	0.01	ns
Output Adjusters					
LVDS25E	LVDS 2.5 E	-0.13	-0.15	-0.18	ns
LVDS25 ⁴	LVDS 2.5	-0.21	-0.26	-0.30	ns
BLVDS25	BLVDS 2.5	-0.03	-0.03	-0.04	ns
LVPECL33	LVPECL 3.3	0.04	0.04	0.05	ns
LVTTTL33_4mA	LVTTTL 4mA drive	0.04	0.04	0.05	ns
LVTTTL33_8mA	LVTTTL 8mA drive	0.06	0.07	0.08	ns
LVTTTL33_12mA	LVTTTL 12mA drive	-0.01	-0.01	-0.01	ns
LVTTTL33_16mA	LVTTTL 16mA drive	0.50	0.60	0.70	ns
LVC MOS33_4mA	LVC MOS 3.3 4mA drive	0.04	0.04	0.05	ns
LVC MOS33_8mA	LVC MOS 3.3 8mA drive	0.06	0.07	0.08	ns
LVC MOS33_12mA	LVC MOS 3.3 12mA drive	-0.01	-0.01	-0.01	ns
LVC MOS33_14mA	LVC MOS 3.3 14mA drive	0.50	0.60	0.70	ns
LVC MOS25_4mA	LVC MOS 2.5 4mA drive	0.05	0.06	0.07	ns
LVC MOS25_8mA	LVC MOS 2.5 8mA drive	0.10	0.12	0.13	ns
LVC MOS25_12mA	LVC MOS 2.5 12mA drive	0.00	0.00	0.00	ns
LVC MOS25_14mA	LVC MOS 2.5 14mA drive	0.34	0.40	0.47	ns
LVC MOS18_4mA	LVC MOS 1.8 4mA drive	0.11	0.13	0.15	ns
LVC MOS18_8mA	LVC MOS 1.8 8mA drive	0.05	0.06	0.06	ns
LVC MOS18_12mA	LVC MOS 1.8 12mA drive	-0.06	-0.07	-0.08	ns
LVC MOS18_14mA	LVC MOS 1.8 14mA drive	0.06	0.07	0.09	ns
LVC MOS15_4mA	LVC MOS 1.5 4mA drive	0.15	0.19	0.22	ns
LVC MOS15_8mA	LVC MOS 1.5 8mA drive	0.05	0.06	0.07	ns
LVC MOS12_2mA	LVC MOS 1.2 2mA drive	0.26	0.31	0.36	ns
LVC MOS12_6mA	LVC MOS 1.2 6mA drive	0.05	0.06	0.07	ns
PCI33 ⁴	PCI33	1.85	2.22	2.59	ns

1. Timing adders are characterized but not tested on every device.

2. LVC MOS timing is measured with the load specified in Switching Test Conditions table.

3. All other standards tested according to the appropriate specifications.

4. I/O standard only available in LCMXO1200 and LCMXO2280 devices.

Rev. A 0.19

LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections: 144 TQFP (Cont.)

Pin Number	LCMXO640				LCMXO1200				LCMXO2280			
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
101	PR3D	1		C	PR4B	2		C*	PR5B	2		C*
102	PR3C	1		T	PR4A	2		T*	PR5A	2		T*
103	PR3B	1		C	PR3D	2		C	PR4D	2		C
104	PR2D	1		C	PR3C	2		T	PR4C	2		T
105	PR3A	1		T	PR3B	2		C*	PR4B	2		C*
106	PR2B	1		C	PR3A	2		T*	PR4A	2		T*
107	PR2C	1		T	PR2B	2		C	PR3B	2		C*
108	PR2A	1		T	PR2A	2		T	PR3A	2		T*
109	PT9F	0		C	PT11D	1		C	PT16D	1		C
110	PT9D	0		C	PT11C	1		T	PT16C	1		T
111	PT9E	0		T	PT11B	1		C	PT16B	1		C
112	PT9B	0		C	PT11A	1		T	PT16A	1		T
113	PT9C	0		T	PT10F	1		C	PT15D	1		C
114	PT9A	0		T	PT10E	1		T	PT15C	1		T
115	PT8C	0			PT10D	1		C	PT14B	1		C
116	PT8B	0		C	PT10C	1		T	PT14A	1		T
117	VCCIO0	0			VCCIO1	1			VCCIO1	1		
118	GNDIO0	0			GNDIO1	1			GNDIO1	1		
119	PT8A	0		T	PT9F	1		C	PT12F	1		C
120	PT7E	0			PT9E	1		T	PT12E	1		T
121	PT7C	0			PT9B	1		C	PT12D	1		C
122	PT7A	0			PT9A	1		T	PT12C	1		T
123	GND	-			GND	-			GND	-		
124	PT6B	0	PCLK0_1***	C	PT7D	1	PCLK1_1***		PT10B	1	PCLK1_1***	
125	PT6A	0		T	PT7B	1		C	PT9D	1		C
126	PT5C	0			PT7A	1		T	PT9C	1		T
127	PT5B	0	PCLK0_0***		PT6F	0	PCLK1_0***		PT9B	1	PCLK1_0***	
128	VCCAUX	-			VCCAUX	-			VCCAUX	-		
129	VCC	-			VCC	-			VCC	-		
130	PT4D	0			PT5D	0		C	PT7B	0		C
131	PT4B	0		C	PT5C	0		T	PT7A	0		T
132	PT4A	0		T	PT5B	0		C	PT6D	0		
133	PT3F	0			PT5A	0		T	PT6E	0		T
134	PT3D	0			PT4B	0			PT6F	0		C
135	VCCIO0	0			VCCIO0	0			VCCIO0	0		
136	GNDIO0	0			GNDIO0	0			GNDIO0	0		
137	PT3B	0		C	PT3D	0		C	PT4B	0		T
138	PT2F	0		C	PT3C	0		T	PT4A	0		C
139	PT3A	0		T	PT3B	0		C	PT3B	0		C
140	PT2D	0		C	PT3A	0		T	PT3A	0		T
141	PT2E	0		T	PT2D	0		C	PT2D	0		C
142	PT2B	0		C	PT2C	0		T	PT2C	0		T
143	PT2C	0		T	PT2B	0		C	PT2B	0		C
144	PT2A	0		T	PT2A	0		T	PT2A	0		T

*Supports true LVDS outputs.

**NC for "E" devices.

***Primary clock inputs are single-ended.

LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections: 256 caBGA / 256 ftBGA (Cont.)

LCMXO640					LCMXO1200					LCMXO2280				
Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential
J4	PL8A	3		T	J4	PL13A	6		T*	J4	PL16A	6		T*
J5	PL8B	3		C	J5	PL13B	6		C*	J5	PL16B	6		C*
R1	PL11A	3		T	R1	PL13C	6		T	R1	PL16C	6		T
R2	PL11B	3		C	R2	PL13D	6		C	R2	PL16D	6		C
-	-	-			-	-	-			GND	GND	-		
K5	NC				K5	PL14A	6	LLM0_PLLT_FB_A	T*	K5	PL17A	6	LLM0_PLLT_FB_A	T*
K4	NC				K4	PL14B	6	LLM0_PLLC_FB_A	C*	K4	PL17B	6	LLM0_PLLC_FB_A	C*
L5	PL10C	3		T	L5	PL14C	6		T	L5	PL17C	6		T
L4	PL10D	3		C	L4	PL14D	6		C	L4	PL17D	6		C
M5	NC				M5	PL15A	6	LLM0_PLLT_IN_A	T*	M5	PL18A	6	LLM0_PLLT_IN_A	T*
M4	NC				M4	PL15B	6	LLM0_PLLC_IN_A	C*	M4	PL18B	6	LLM0_PLLC_IN_A	C*
N4	PL11C	3		T	N4	PL16A	6		T	N4	PL19A	6		T
N3	PL11D	3		C	N3	PL16B	6		C	N3	PL19B	6		C
VCCIO3	VCCIO3	3			VCCIO6	VCCIO6	6			VCCIO6	VCCIO6	6		
GND	GNDIO3	3			GND	GNDIO6	6			GND	GNDIO6	6		
GND	GNDIO2	2			GND	GNDIO5	5			GND	GNDIO5	5		
VCCIO2	VCCIO2	2			VCCIO5	VCCIO5	5			VCCIO5	VCCIO5	5		
P4	TMS	2	TMS		P4	TMS	5	TMS		P4	TMS	5	TMS	
P2	NC				P2	PB2A	5		T	P2	PB2A	5		T
P3	NC				P3	PB2B	5		C	P3	PB2B	5		C
N5	NC				N5	PB2C	5		T	N5	PB2C	5		T
R3	TCK	2	TCK		R3	TCK	5	TCK		R3	TCK	5	TCK	
N6	NC				N6	PB2D	5		C	N6	PB2D	5		C
T2	PB2A	2		T	T2	PB3A	5		T	T2	PB3A	5		T
T3	PB2B	2		C	T3	PB3B	5		C	T3	PB3B	5		C
R4	PB2C	2		T	R4	PB3C	5		T	R4	PB3C	5		T
R5	PB2D	2		C	R5	PB3D	5		C	R5	PB3D	5		C
P5	PB3A	2		T	P5	PB4A	5		T	P5	PB4A	5		T
P6	PB3B	2		C	P6	PB4B	5		C	P6	PB4B	5		C
T5	PB3C	2		T	T5	PB4C	5		T	T5	PB4C	5		T
M6	TDO	2	TDO		M6	TDO	5	TDO		M6	TDO	5	TDO	
T4	PB3D	2		C	T4	PB4D	5		C	T4	PB4D	5		C
R6	PB4A	2		T	R6	PB5A	5		T	R6	PB5A	5		T
GND	GNDIO2	2			GND	GNDIO5	5			GND	GNDIO5	5		
VCCIO2	VCCIO2	2			VCCIO5	VCCIO5	5			VCCIO5	VCCIO5	5		
T6	PB4B	2		C	T6	PB5B	5		C	T6	PB5B	5		C
N7	TDI	2	TDI		N7	TDI	5	TDI		N7	TDI	5	TDI	
T8	PB4C	2		T	T8	PB5C	5		T	T8	PB6A	5		T
T7	PB4D	2		C	T7	PB5D	5		C	T7	PB6B	5		C
M7	NC				M7	PB6A	5		T	M7	PB7C	5		T
M8	NC				M8	PB6B	5		C	M8	PB7D	5		C
T9	VCCAUX	-			T9	VCCAUX	-			T9	VCCAUX	-		
R7	PB4E	2		T	R7	PB6C	5		T	R7	PB8C	5		T
R8	PB4F	2		C	R8	PB6D	5		C	R8	PB8D	5		C
-	-				VCCIO5	VCCIO5	5			VCCIO5	VCCIO5	5		
-	-				GND	GNDIO5	5			GND	GNDIO5	5		
P7	PB5C	2		T	P7	PB6E	5		T	P7	PB9A	4		T
P8	PB5D	2		C	P8	PB6F	5		C	P8	PB9B	4		C
N8	PB5A	2		T	N8	PB7A	4		T	N8	PB10E	4		T
N9	PB5B	2	PCLK2_1***	C	N9	PB7B	4	PCLK4_1***	C	N9	PB10F	4	PCLK4_1***	C
P10	PB7B	2		C	P10	PB7D	4		C	P10	PB10D	4		C
P9	PB7A	2		T	P9	PB7C	4		T	P9	PB10C	4		T
M9	PB6B	2	PCLK2_0***	C	M9	PB7F	4	PCLK4_0***	C	M9	PB10B	4	PCLK4_0***	C

LCMX02280 Logic Signal Connections: 324 ftBGA (Cont.)

LCMX02280				
Ball Number	Ball Function	Bank	Dual Function	Differential
GND	GNDIO3	3		
VCCIO3	VCCIO3	3		
P15	PR20B	3		C
N14	PR20A	3		T
N15	PR19B	3		C
M13	PR19A	3		T
R15	PR18B	3		C*
T16	PR18A	3		T*
N16	PR17D	3		C
M14	PR17C	3		T
U17	PR17B	3		C*
VCC	VCC	-		
U18	PR17A	3		T*
R17	PR16D	3		C
R16	PR16C	3		T
P16	PR16B	3		C*
VCCIO3	VCCIO3	3		
GND	GNDIO3	3		
P17	PR16A	3		T*
L13	PR15D	3		C
M15	PR15C	3		T
T17	PR15B	3		C*
T18	PR15A	3		T*
L14	PR14D	3		C
L15	PR14C	3		T
R18	PR14B	3		C*
P18	PR14A	3		T*
GND	GND	-		
K15	PR13D	3		C
K13	PR13C	3		T
N17	PR13B	3		C*
N18	PR13A	3		T*
K16	PR12D	3		C
K14	PR12C	3		T
M16	PR12B	3		C*
L16	PR12A	3		T*
GND	GNDIO3	3		
VCCIO3	VCCIO3	3		
J16	PR11D	3		C
J14	PR11C	3		T
M17	PR11B	3		C*
L17	PR11A	3		T*
J15	PR10D	2		C

Thermal Management

Thermal management is recommended as part of any sound FPGA design methodology. To assess the thermal characteristics of a system, Lattice specifies a maximum allowable junction temperature in all device data sheets. Designers must complete a thermal analysis of their specific design to ensure that the device and package do not exceed the junction temperature limits. Refer to the [Thermal Management](#) document to find the device/package specific thermal values.

For Further Information

For further information regarding Thermal Management, refer to the following:

- [Thermal Management](#) document
- TN1090 - [Power Estimation and Management for MachXO Devices](#)
- Power Calculator tool included with the Lattice ispLEVER design tool, or as a standalone download from www.latticesemi.com/software

Lead-Free Packaging
Commercial

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO256C-3TN100C	256	1.8V/2.5V/3.3V	78	-3	Lead-Free TQFP	100	COM
LCMXO256C-4TN100C	256	1.8V/2.5V/3.3V	78	-4	Lead-Free TQFP	100	COM
LCMXO256C-5TN100C	256	1.8V/2.5V/3.3V	78	-5	Lead-Free TQFP	100	COM
LCMXO256C-3MN100C	256	1.8V/2.5V/3.3V	78	-3	Lead-Free csBGA	100	COM
LCMXO256C-4MN100C	256	1.8V/2.5V/3.3V	78	-4	Lead-Free csBGA	100	COM
LCMXO256C-5MN100C	256	1.8V/2.5V/3.3V	78	-5	Lead-Free csBGA	100	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO640C-3TN100C	640	1.8V/2.5V/3.3V	74	-3	Lead-Free TQFP	100	COM
LCMXO640C-4TN100C	640	1.8V/2.5V/3.3V	74	-4	Lead-Free TQFP	100	COM
LCMXO640C-5TN100C	640	1.8V/2.5V/3.3V	74	-5	Lead-Free TQFP	100	COM
LCMXO640C-3MN100C	640	1.8V/2.5V/3.3V	74	-3	Lead-Free csBGA	100	COM
LCMXO640C-4MN100C	640	1.8V/2.5V/3.3V	74	-4	Lead-Free csBGA	100	COM
LCMXO640C-5MN100C	640	1.8V/2.5V/3.3V	74	-5	Lead-Free csBGA	100	COM
LCMXO640C-3TN144C	640	1.8V/2.5V/3.3V	113	-3	Lead-Free TQFP	144	COM
LCMXO640C-4TN144C	640	1.8V/2.5V/3.3V	113	-4	Lead-Free TQFP	144	COM
LCMXO640C-5TN144C	640	1.8V/2.5V/3.3V	113	-5	Lead-Free TQFP	144	COM
LCMXO640C-3MN132C	640	1.8V/2.5V/3.3V	101	-3	Lead-Free csBGA	132	COM
LCMXO640C-4MN132C	640	1.8V/2.5V/3.3V	101	-4	Lead-Free csBGA	132	COM
LCMXO640C-5MN132C	640	1.8V/2.5V/3.3V	101	-5	Lead-Free csBGA	132	COM
LCMXO640C-3BN256C	640	1.8V/2.5V/3.3V	159	-3	Lead-Free caBGA	256	COM
LCMXO640C-4BN256C	640	1.8V/2.5V/3.3V	159	-4	Lead-Free caBGA	256	COM
LCMXO640C-5BN256C	640	1.8V/2.5V/3.3V	159	-5	Lead-Free caBGA	256	COM
LCMXO640C-3FTN256C	640	1.8V/2.5V/3.3V	159	-3	Lead-Free ftBGA	256	COM
LCMXO640C-4FTN256C	640	1.8V/2.5V/3.3V	159	-4	Lead-Free ftBGA	256	COM
LCMXO640C-5FTN256C	640	1.8V/2.5V/3.3V	159	-5	Lead-Free ftBGA	256	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO1200C-3TN100C	1200	1.8V/2.5V/3.3V	73	-3	Lead-Free TQFP	100	COM
LCMXO1200C-4TN100C	1200	1.8V/2.5V/3.3V	73	-4	Lead-Free TQFP	100	COM
LCMXO1200C-5TN100C	1200	1.8V/2.5V/3.3V	73	-5	Lead-Free TQFP	100	COM
LCMXO1200C-3TN144C	1200	1.8V/2.5V/3.3V	113	-3	Lead-Free TQFP	144	COM
LCMXO1200C-4TN144C	1200	1.8V/2.5V/3.3V	113	-4	Lead-Free TQFP	144	COM
LCMXO1200C-5TN144C	1200	1.8V/2.5V/3.3V	113	-5	Lead-Free TQFP	144	COM
LCMXO1200C-3MN132C	1200	1.8V/2.5V/3.3V	101	-3	Lead-Free csBGA	132	COM
LCMXO1200C-4MN132C	1200	1.8V/2.5V/3.3V	101	-4	Lead-Free csBGA	132	COM
LCMXO1200C-5MN132C	1200	1.8V/2.5V/3.3V	101	-5	Lead-Free csBGA	132	COM
LCMXO1200C-3BN256C	1200	1.8V/2.5V/3.3V	211	-3	Lead-Free caBGA	256	COM
LCMXO1200C-4BN256C	1200	1.8V/2.5V/3.3V	211	-4	Lead-Free caBGA	256	COM
LCMXO1200C-5BN256C	1200	1.8V/2.5V/3.3V	211	-5	Lead-Free caBGA	256	COM
LCMXO1200C-3FTN256C	1200	1.8V/2.5V/3.3V	211	-3	Lead-Free ftBGA	256	COM
LCMXO1200C-4FTN256C	1200	1.8V/2.5V/3.3V	211	-4	Lead-Free ftBGA	256	COM
LCMXO1200C-5FTN256C	1200	1.8V/2.5V/3.3V	211	-5	Lead-Free ftBGA	256	COM

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO256E-3TN100I	256	1.2V	78	-3	Lead-Free TQFP	100	IND
LCMXO256E-4TN100I	256	1.2V	78	-4	Lead-Free TQFP	100	IND
LCMXO256E-3MN100I	256	1.2V	78	-3	Lead-Free csBGA	100	IND
LCMXO256E-4MN100I	256	1.2V	78	-4	Lead-Free csBGA	100	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO640E-3TN100I	640	1.2V	74	-3	Lead-Free TQFP	100	IND
LCMXO640E-4TN100I	640	1.2V	74	-4	Lead-Free TQFP	100	IND
LCMXO640E-3MN100I	640	1.2V	74	-3	Lead-Free csBGA	100	IND
LCMXO640E-4MN100I	640	1.2V	74	-4	Lead-Free csBGA	100	IND
LCMXO640E-3TN144I	640	1.2V	113	-3	Lead-Free TQFP	144	IND
LCMXO640E-4TN144I	640	1.2V	113	-4	Lead-Free TQFP	144	IND
LCMXO640E-3MN132I	640	1.2V	101	-3	Lead-Free csBGA	132	IND
LCMXO640E-4MN132I	640	1.2V	101	-4	Lead-Free csBGA	132	IND
LCMXO640E-3BN256I	640	1.2V	159	-3	Lead-Free caBGA	256	IND
LCMXO640E-4BN256I	640	1.2V	159	-4	Lead-Free caBGA	256	IND
LCMXO640E-3FTN256I	640	1.2V	159	-3	Lead-Free ftBGA	256	IND
LCMXO640E-4FTN256I	640	1.2V	159	-4	Lead-Free ftBGA	256	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO1200E-3TN100I	1200	1.2V	73	-3	Lead-Free TQFP	100	IND
LCMXO1200E-4TN100I	1200	1.2V	73	-4	Lead-Free TQFP	100	IND
LCMXO1200E-3TN144I	1200	1.2V	113	-3	Lead-Free TQFP	144	IND
LCMXO1200E-4TN144I	1200	1.2V	113	-4	Lead-Free TQFP	144	IND
LCMXO1200E-3MN132I	1200	1.2V	101	-3	Lead-Free csBGA	132	IND
LCMXO1200E-4MN132I	1200	1.2V	101	-4	Lead-Free csBGA	132	IND
LCMXO1200E-3BN256I	1200	1.2V	211	-3	Lead-Free caBGA	256	IND
LCMXO1200E-4BN256I	1200	1.2V	211	-4	Lead-Free caBGA	256	IND
LCMXO1200E-3FTN256I	1200	1.2V	211	-3	Lead-Free ftBGA	256	IND
LCMXO1200E-4FTN256I	1200	1.2V	211	-4	Lead-Free ftBGA	256	IND

Part Number	LUTs	Supply Voltage	I/Os	Grade	Package	Pins	Temp.
LCMXO2280E-3TN100I	2280	1.2V	73	-3	Lead-Free TQFP	100	IND
LCMXO2280E-4TN100I	2280	1.2V	73	-4	Lead-Free TQFP	100	IND
LCMXO2280E-3TN144I	2280	1.2V	113	-3	Lead-Free TQFP	144	IND
LCMXO2280E-4TN144I	2280	1.2V	113	-4	Lead-Free TQFP	144	IND
LCMXO2280E-3MN132I	2280	1.2V	101	-3	Lead-Free csBGA	132	IND
LCMXO2280E-4MN132I	2280	1.2V	101	-4	Lead-Free csBGA	132	IND
LCMXO2280E-3BN256I	2280	1.2V	211	-3	Lead-Free caBGA	256	IND
LCMXO2280E-4BN256I	2280	1.2V	211	-4	Lead-Free caBGA	256	IND
LCMXO2280E-3FTN256I	2280	1.2V	211	-3	Lead-Free ftBGA	256	IND
LCMXO2280E-4FTN256I	2280	1.2V	211	-4	Lead-Free ftBGA	256	IND
LCMXO2280E-3FTN324I	2280	1.2V	271	-3	Lead-Free ftBGA	324	IND
LCMXO2280E-4FTN324I	2280	1.2V	271	-4	Lead-Free ftBGA	324	IND

For Further Information

A variety of technical notes for the MachXO family are available on the Lattice web site.

- TN1091, [MachXO sysIO Usage Guide](#)
- TN1089, [MachXO sysCLOCK Design and Usage Guide](#)
- TN1092, [Memory Usage Guide for MachXO Devices](#)
- TN1090, [Power Estimation and Management for MachXO Devices](#)
- TN1086, [MachXO JTAG Programming and Configuration User's Guide](#)
- TN1087, [Minimizing System Interruption During Configuration Using TransFR Technology](#)
- TN1097, [MachXO Density Migration](#)
- AN8066, [Boundary Scan Testability with Lattice sysIO Capability](#)

For further information on interface standards refer to the following web sites:

- JEDEC Standards (LVTTTL, LVCMOS): www.jedec.org
- PCI: www.pcisig.com

Revision History

Date	Version	Section	Change Summary
February 2005	01.0	—	Initial release.
October 2005	01.1	Introduction	Distributed RAM information in family table updated. Added footnote 1 - fpBGA packaging to the family selection guide.
		Architecture	sysIO Buffer section updated.
			Hot Socketing section updated.
			Sleep Mode section updated.
			SLEEP Pin Characteristics section updated.
			Oscillator section updated.
			Security section updated.
		DC and Switching Characteristics	Recommended Operating Conditions table updated.
			DC Electrical Characteristics table updated.
			Supply Current (Sleep Mode) table added with LCMXO256/640 data.
			Supply Current (Standby) table updated with LCMXO256/640 data.
			Initialization Supply Current table updated with LCMXO256/640 data.
			Programming and Erase Flash Supply Current table updated with LCMXO256/640 data.
			Register-to-Register Performance table updated (rev. A 0.16).
			External Switching Characteristics table updated (rev. A 0.16).
			Internal Timing Parameter table updated (rev. A 0.16).
			Family Timing Adders updated (rev. A 0.16).
			sysCLOCK Timing updated (rev. A 0.16).
			MachXO "C" Sleep Mode Timing updated (A 0.16).
			JTAG Port Timing Specification updated (rev. A 0.16).
		Pinout Information	SLEEPIN description updated.
			Pin Information Summary updated.
			Power Supply and NC Connection table has been updated.
			Logic Signal Connection section has been updated to include all devices/packages.
		Ordering Information	Part Number Description section has been updated.
			Ordering Part Number section has been updated (added LCMXO256C/LCMXO640C "4W").
		Supplemental Information	MachXO Density Migration Technical Note (TN1097) added.
November 2005	01.2	Pinout Information	Added "Power Supply and NC Connections" summary information for LCMXO1200 and LCMXO2280 in 100 TQFP package.
December 2005	01.3	DC and Switching Characteristics	Supply Current (Standby) table updated with LCMXO1200/2280 data.
		Ordering Information	Ordering Part Number section updated (added LCMXO2280C "4W").
April 2006	02.0	Introduction	Introduction paragraphs updated.
		Architecture	Architecture Overview paragraphs updated.